one of said terminal-forming areas including a plurality of terminal parts directly thereon such that each pair of said terminal parts within any one of said terminal-forming areas is closer to each other than any pair of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.

REMARKS

Claims 1, 2, 4, 6 and 7 currently remain in the application. Claims 3, 5, 8 and 9 have been withdrawn as non-elected claims. Claim 1 is amended herein.

The abstract section has been rewritten in response to the requirement in Paragraph 1 of the Official Letter.

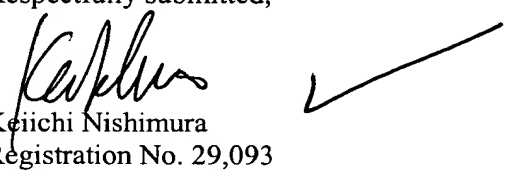
Claims 1, 2, 4, 6 and 7 were rejected under 35 U.S.C. 103 over Matsui in view of Tate. In part in view of these references, independent claim 1 is herein amended to say that the "terminal-forming areas" such as shown at 3a, 3b and 3c are each no greater than the corresponding one of the electronic components such as shown at D1, D2 and D3.

Tate shows in Figs. 13-15 that the body portion 29 of the surface-mounted electronic component 28 are smaller than the area for terminals to be formed. The idea of making the terminal-forming area smaller is not disclosed or even hinted at. It should be clear that it is not a mere matter of design choice but of a practical important to specify a smaller area for mounting a larger component. It is therefore believed that the invention as limited by amended claim 1 is not obvious in view of the cited references.

With independent claim 1 thus amended, it is believed that the application is now believed to be in condition for allowance.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

Respectfully submitted,



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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

Paragraph starting at line 1 of page 13 has been amended as follows:

A plurality of electronic components having conductive connecting members are surface-mounted to a target surface of a circuit board ~~in a plurality of specified terminal-forming areas each having terminal parts.~~ by specifying terminal-forming areas that are each no greater than the corresponding one of the electronic components and each include at least one terminal part such that at least one of these terminal-forming areas includes a plurality of terminal parts directly and that each pair of the terminal parts within any one of the terminal-forming areas is closer to each other than any pair of the terminal parts in different ones of the terminal-forming areas. An anisotropic conductive layer is formed on this target surface so as to span these terminal-forming areas, and the plurality of electronic components are placed on this anisotropic conductive layer individually above the plurality of terminal-forming areas. As the layer is heated, these electronic components are pressed against the layer such that the conductive connecting members of the electronic components become attached to and electrically conductive with corresponding ones of the terminal parts on the circuit board. The anisotropic conductive layer remains electrically insulative elsewhere.

IN THE CLAIMS:

Claim 1 has been amended as follows:

1. (Five times amended) A method of surface-mounting a plurality of electronic components having conductive connecting members, said method comprising the steps of:

providing a target surface having a plurality of specified terminal-forming areas thereon, each of said specified terminal-forming areas being no greater than corresponding one of said electronic components and including at least one terminal part therein, at least one of said terminal-forming areas including a plurality of terminal parts directly thereon such that each pair of said terminal parts within any one of said terminal-forming areas is closer to each other than any pair of said terminal parts in different ones of said terminal-forming areas;

forming an anisotropic conductive layer on said target surface so as to span said plurality of terminal-forming areas;

placing said plurality of electronic components on said anisotropic conductive layer individually above said plurality of terminal-forming areas; and

pressing said plurality of electronic components to said anisotropic conductive layer so as to thereby cause said conductive connecting members of said plurality of electronic components to individually become adhered to and in electrically conductive relationship with a corresponding one of said terminal parts through said anisotropic conductive layer.